

Silicon Carbide (SiC) MOSFET – EliteSiC, 22 mohm, 1200 V, M3S, D²PAK-7L

NTBG022N120M3S

Features

- Typ. $R_{DS(on)} = 22\text{ m}\Omega$
- Ultra Low Gate Charge ($Q_{G(tot)} = 151\text{ nC}$)
- High Speed Switching with Low Capacitance ($C_{oss} = 146\text{ pF}$)
- 100% Avalanche Tested
- These Devices are RoHS Compliant

Typical Applications

- Solar Inverters
- Electric Vehicle Charging Stations
- Uninterruptible Power Supplies (UPS)
- Energy Storage Systems
- Switch Mode Power Supplies (SMPS)

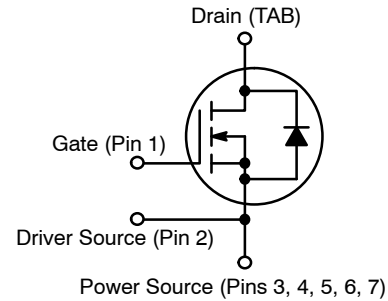
MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit	
Drain-to-Source Voltage		V_{DSS}	1200	V	
Gate-to-Source Voltage		V_{GS}	-10/+22	V	
Recommended Operation Values of Gate-to-Source Voltage		$T_C < 175^\circ\text{C}$ V_{GSop}	-3/+18	V	
Continuous Drain Current (Notes 2, 3)	Steady State	$T_C = 25^\circ\text{C}$	I_D	72	A
			P_D	234	W
Power Dissipation $R_{\theta JC}$ (Note 2)	Steady State	$T_C = 100^\circ\text{C}$	I_D	51	A
			P_D	117	W
Pulsed Drain Current (Note 4)	$T_C = 25^\circ\text{C}$		I_{DM}	171	A
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to +175	$^\circ\text{C}$	
Source Current (Body Diode) $T_C = 25^\circ\text{C}, V_{GS} = -3\text{ V}$ (Note 2)		I_S	53	A	
Single Pulse Drain-to-Source Avalanche Energy ($I_{L(pk)} = 23.1\text{ A}, L = 1\text{ mH}$) (Note 5)		E_{AS}	267	mJ	
Maximum Temperature for Soldering (10 s)		T_L	270	$^\circ\text{C}$	

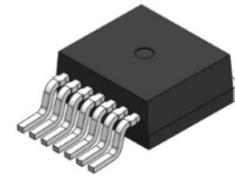
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface mounted on a FR-4 board using 1 in² pad of 2 oz copper.
2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
3. The maximum current rating is based on typical $R_{DS(on)}$ performance.
4. Repetitive rating, limited by max junction temperature.
5. E_{AS} of 264 mJ is based on starting $T_J = 25^\circ\text{C}$; $L = 1\text{ mH}$, $I_{AS} = 23.1\text{ A}$, $V_{DD} = 100\text{ V}$, $V_{GS} = 18\text{ V}$.

$V_{(BR)DSS}$	$R_{DS(ON)}\text{ MAX}$	$I_D\text{ MAX}$
1200 V	30 m Ω @ 18 V	72 A

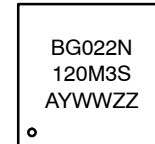


N-CHANNEL MOSFET



D²PAK-7L
CASE 418BJ

MARKING DIAGRAM



BG022N120M3S = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping
NTBG022N120M3S	D ² PAK-7L	800 / Tape & Reel

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THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Max	Unit
Junction-to-Case – Steady State (Note 2)	$R_{\theta JC}$	0.64	–	°C/W
Junction-to-Ambient – Steady State (Notes 1, 2)	$R_{\theta JA}$	–	40	

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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OFF-STATE CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	1200	–	–	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	$I_D = 1\text{ mA}$, referenced to 25°C (Note 7)	–	0.3	–	V/°C
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0\text{ V}, V_{DS} = 1200\text{ V}, T_J = 25^\circ\text{C}$	–	–	100	μA
Gate-to-Source Leakage Current	I_{GSS}	$V_{GS} = +22/-10\text{ V}, V_{DS} = 0\text{ V}$	–	–	± 1	μA

ON-STATE CHARACTERISTICS

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 20\text{ mA}$	2.04	2.72	4.4	V
Recommended Gate Voltage	V_{GOP}		–3	–	+18	V
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 18\text{ V}, I_D = 40\text{ A}, T_J = 25^\circ\text{C}$	–	22	30	m Ω
		$V_{GS} = 18\text{ V}, I_D = 40\text{ A}, T_J = 175^\circ\text{C}$ (Note 7)	–	44	–	
Forward Transconductance	g_{FS}	$V_{DS} = 10\text{ V}, I_D = 40\text{ A}$ (Note 7)	–	34	–	S

CHARGES, CAPACITANCES & GATE RESISTANCE

Input Capacitance	C_{ISS}	$V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 800\text{ V}$	–	3175	–	pF
Output Capacitance	C_{OSS}		–	146	–	
Reverse Transfer Capacitance	C_{RSS}		–	14	–	
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -3/18\text{ V}, V_{DS} = 800\text{ V}, I_D = 40\text{ A}$	–	151	–	nC
Threshold Gate Charge	$Q_{G(TH)}$		–	20	–	
Gate-to-Source Charge	Q_{GS}		–	34	–	
Gate-to-Drain Charge	Q_{GD}		–	40	–	
Gate-Resistance	R_G	$f = 1\text{ MHz}$	–	1.5	–	Ω

SWITCHING CHARACTERISTICS

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -3/18\text{ V}, V_{DS} = 800\text{ V}, I_D = 40\text{ A}, R_G = 4.5\text{ }\Omega$ inductive load (Notes 6, 7)	–	18	–	ns
Rise Time	t_r		–	24	–	
Turn-Off Delay Time	$t_{d(OFF)}$		–	47	–	
Fall Time	t_f		–	14	–	
Turn-On Switching Loss	E_{ON}		–	485	–	μJ
Turn-Off Switching Loss	E_{OFF}		–	220	–	
Total Switching Loss	E_{tot}		–	705	–	

SOURCE-DRAIN DIODE CHARACTERISTICS

Continuous Source-Drain Diode Forward Current (Note 2)	I_{SD}	$V_{GS} = -3\text{ V}, T_C = 25^\circ\text{C}$ (Note 7)	–	–	53	A
Pulsed Source-Drain Diode Forward Current (Note 4)	I_{SDM}		–	–	171	
Forward Diode Voltage	V_{SD}	$V_{GS} = -3\text{ V}, I_{SD} = 40\text{ A}, T_J = 25^\circ\text{C}$	–	4.5	–	V

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ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified) (continued)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SOURCE-DRAIN DIODE CHARACTERISTICS						
Reverse Recovery Time	t _{RR}	V _{GS} = -3/18 V, I _{SD} = 40 A, di _S /dt = 1000 A/μs, V _{DS} = 800 V (Note 7)	-	23	-	ns
Reverse Recovery Charge	Q _{RR}		-	146	-	nC
Reverse Recovery Energy	E _{REC}		-	5	-	μJ
Peak Reverse Recovery Current	I _{RRM}		-	13	-	A
Charge time	t _A		-	13	-	ns
Discharge time	t _B		-	10	-	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

6. E_{ON}/E_{OFF} result is with body diode

7. Defined by design, not subject to production test.

TYPICAL CHARACTERISTICS

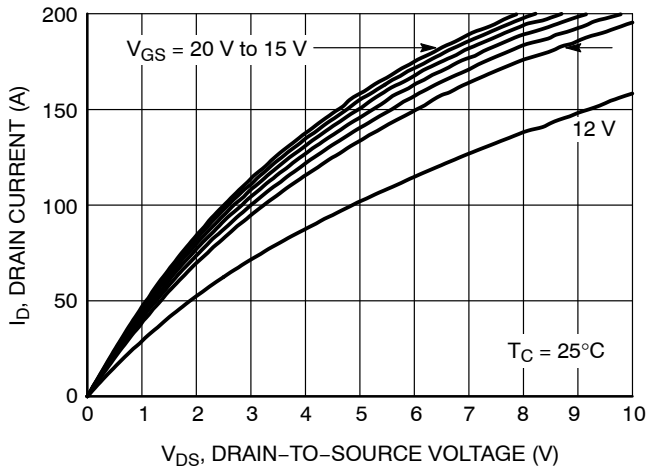


Figure 1. On-Region Characteristics

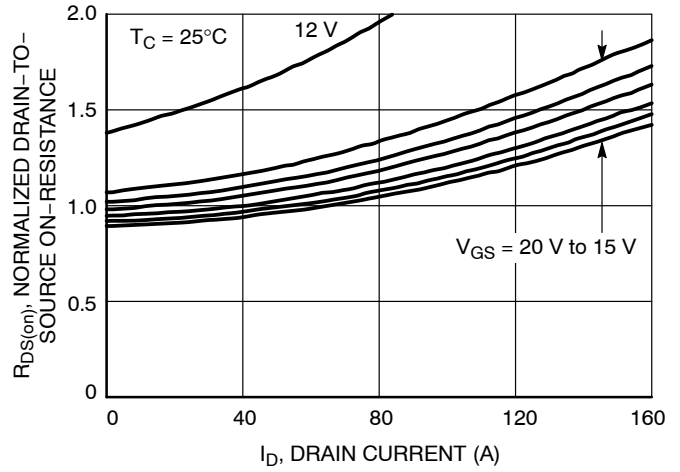


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

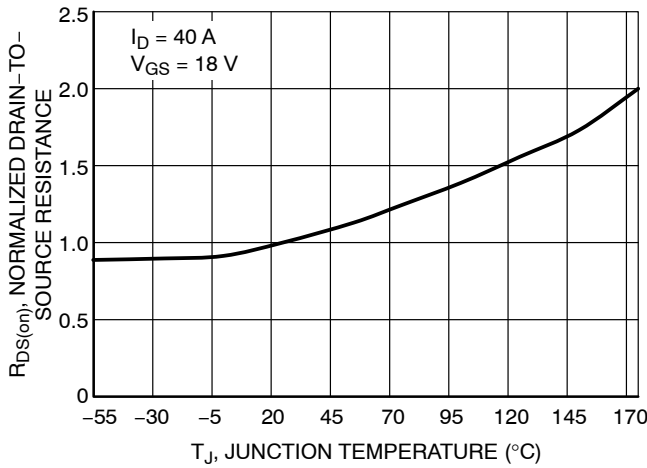


Figure 3. On-Resistance Variation with Temperature

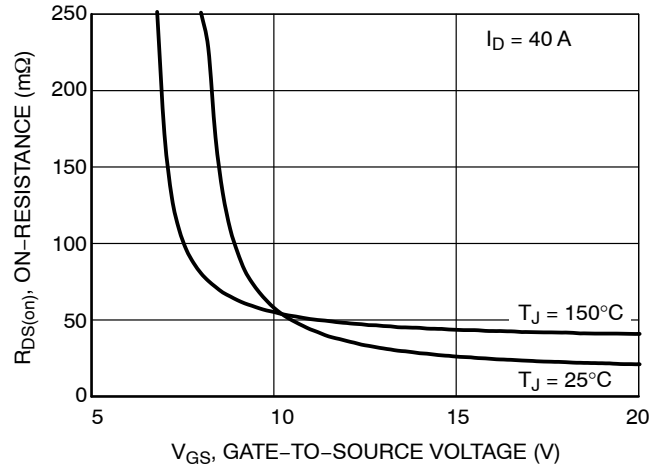


Figure 4. On-Resistance vs. Gate-to-Source Voltage

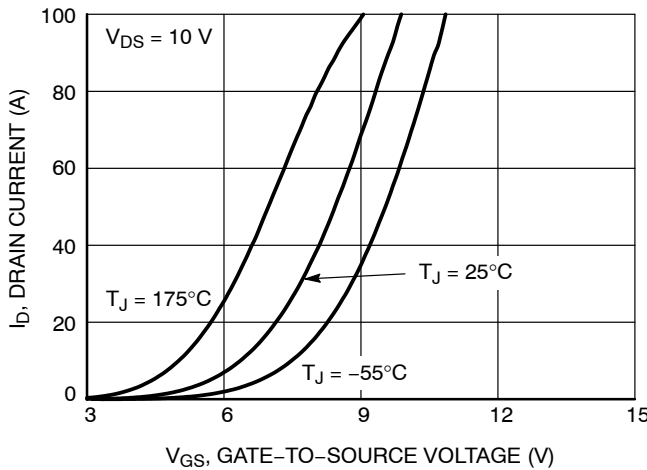


Figure 5. Transfer Characteristics

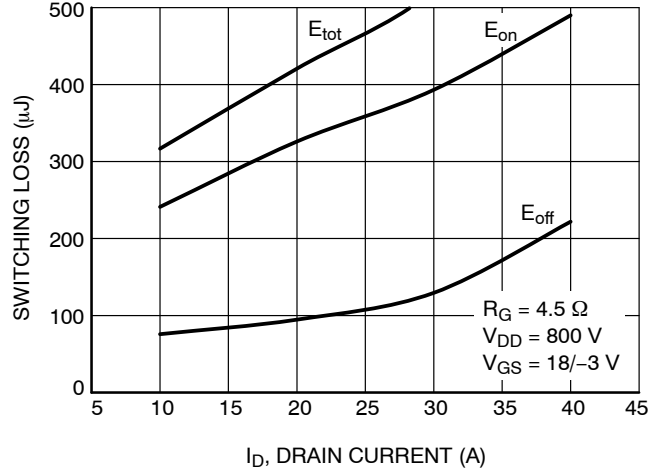


Figure 6. Switching Loss vs. Drain Current

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TYPICAL CHARACTERISTICS

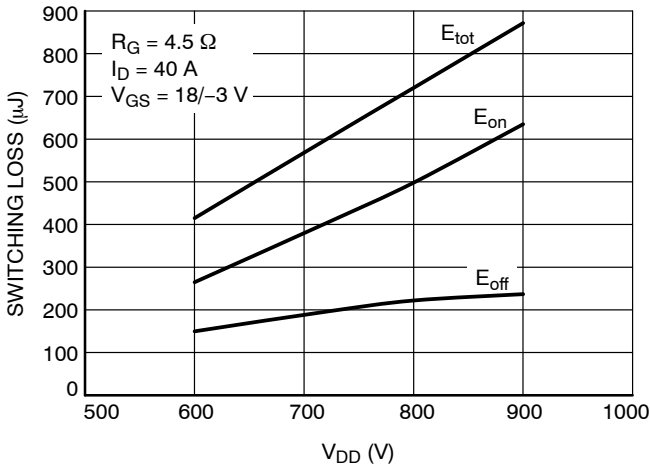


Figure 7. Switching Loss vs. Drain Voltage

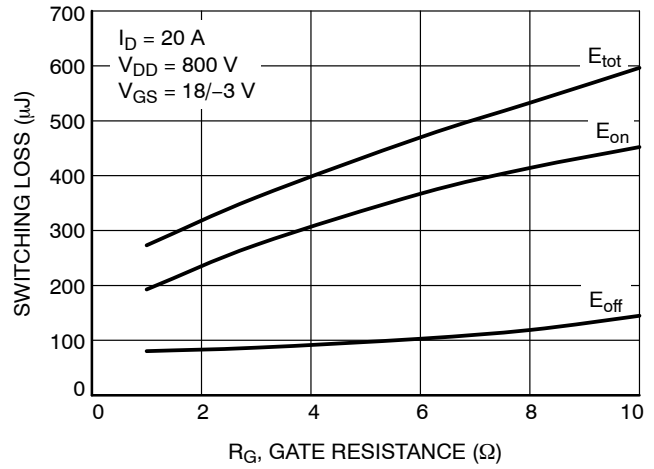


Figure 8. Switching Loss vs. Gate Resistance

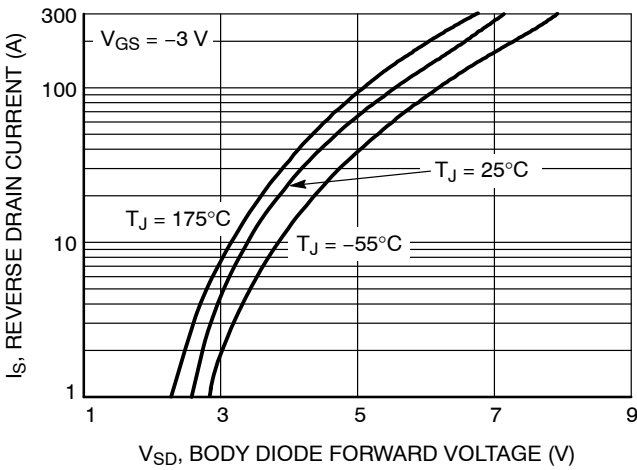


Figure 9. Diode Forward Voltage vs. Current

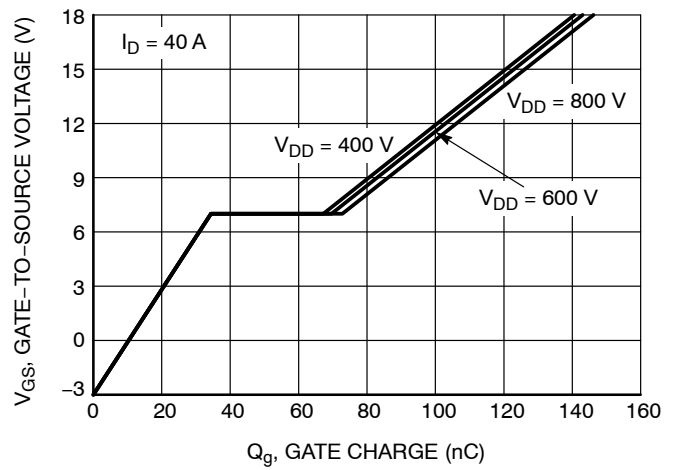


Figure 10. Gate-to-Source Voltage vs. Total Charge

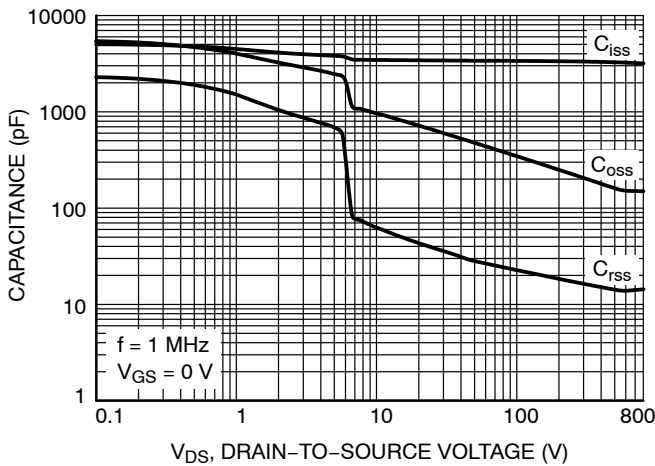


Figure 11. Capacitance vs. Drain-to-Source Voltage

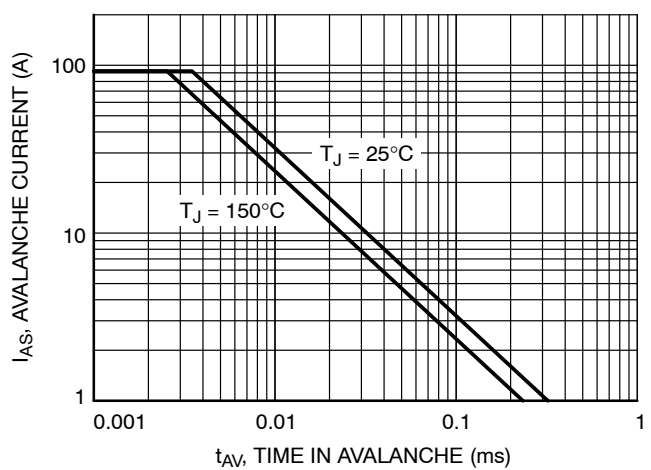


Figure 12. Unclamped Inductive Switching Capability

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TYPICAL CHARACTERISTICS

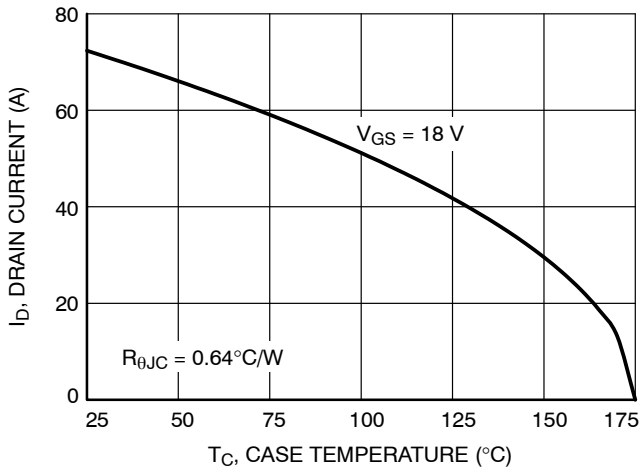


Figure 13. Maximum Continuous Drain Current vs. Case Temperature

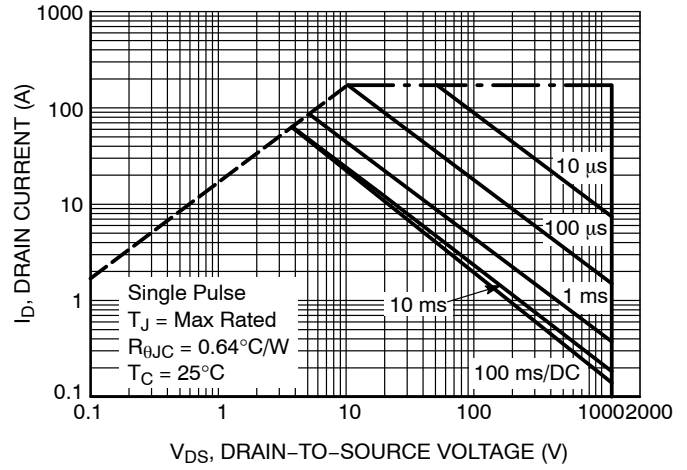


Figure 14. Safe Operating Area

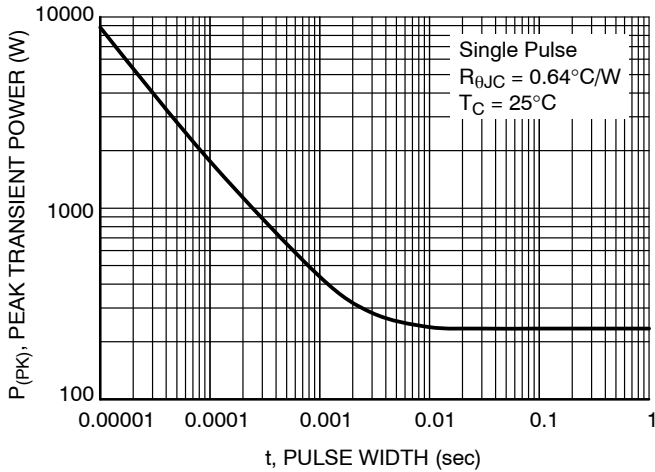


Figure 15. Single Pulse Maximum Power Dissipation

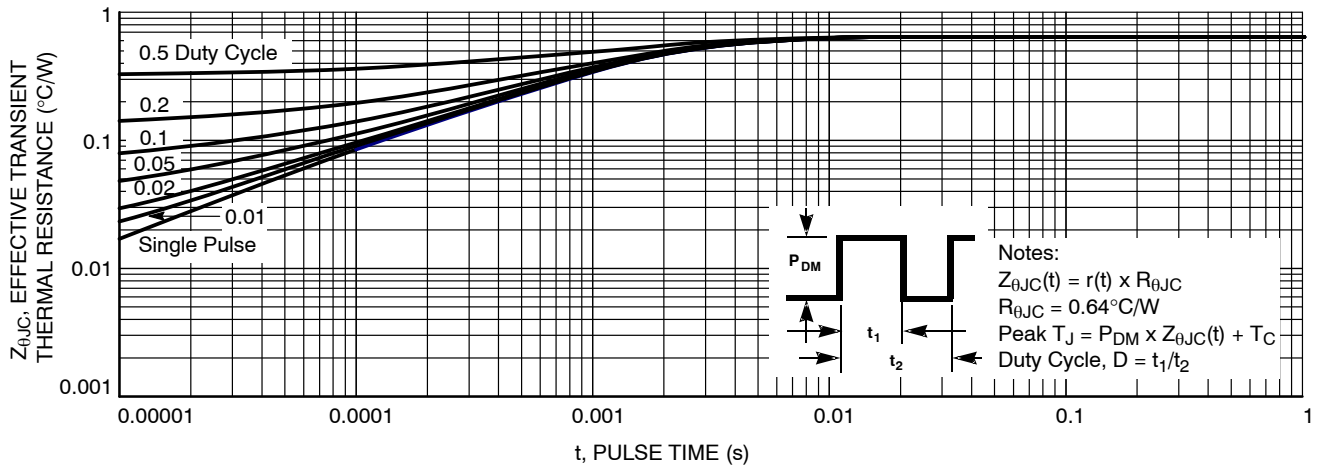


Figure 16. Junction-to-Case Transient Thermal Response

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



D²PAK7 (TO-263-7L HV) CASE 418BJ ISSUE B

DATE 16 AUG 2019



NOTES:

- A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION CB EXCEPT WHERE NOTED.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- \triangle OUT OF JEDEC STANDARD VALUE.
- D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.
- E. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	0.00	0.10	0.20
b2	0.60	0.70	0.80
b	0.51	0.60	0.70
c	0.40	0.50	0.60
c2	1.20	1.30	1.40
D	9.00	9.20	9.40
D1	6.15	6.80	7.15
E	9.70	9.90	10.20
E1	7.15	7.65	8.15
e	~	1.27	~
H	15.10	15.40	15.70
L	2.44	2.64	2.84
L1	1.00	1.20	1.40
L3	~	0.25	~
aaa	~	~	0.25

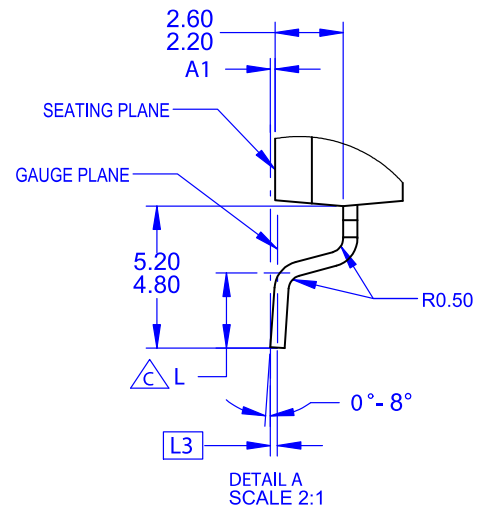


GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



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